

This listing of claims replaces all prior versions, and listings of claims in the instant application:

Listing of Claims:

1. (Currently amended) ~~The~~ An electronic component package of Claim 24 wherein said ~~comprising:~~

~~a substrate comprising~~ substrate further comprises:

~~a first surface;~~

a second surface; and

~~a side;~~

a ground shield extending from said first surface to said second surface ~~and adjacent said side;~~

~~a shield ring coupled to said first surface of said substrate, said shield ring comprising upper ground traces; and~~

~~an electronic component coupled to said first surface.~~

2. (original) The electronic component package of Claim 1 wherein said ground shield comprises a plurality of electrically conductive ground vias.

3. (Previously presented) The electronic component package of Claim 2 wherein said ground vias are spaced sufficiently close to one another to prevent radiation from passing between said ground vias.

4. (original) The electronic component package of Claim 1 wherein said ground shield extends around a periphery of said substrate.

5-6. (Canceled)

7. (Currently amended) The electronic component package of Claim [[1]] 24 wherein said first shield ring comprises upper ground traces ~~are adjacent said side of said substrate.~~

8. (Canceled)

9. (Currently amended) The electronic component package of Claim [[8]] 24 wherein said first shield comprises a shield connection surface, said electronic component package further comprising an electrically conductive adhesive coupling said shield connection surface to said first shield ring.

10. (Canceled)

11. (Currently amended) The electronic component package of Claim ~~10~~ 24 wherein said first shield comprises a shield connection surface, said first shield ring corresponding in shape to said shield connection surface.

12. (original) The electronic component package of Claim 11 wherein said shield connection surface comprises a rectangular annulus.

13-23. (canceled)

24. (Previously presented) An electronic component package comprising:

a substrate comprising a first surface comprising a first central region defined by a first shield ring;

a first shield electrically coupled to said first shield ring, said first shield being continuous;

a first electronic component coupled to said first central region;

a second shield ring defining a second central region of said first surface of said substrate;

a second electronic component coupled to said second central region; and

a second shield enclosing said second electronic component, said second shield being electrically coupled to said second shield ring.

25. (Original) The electronic component package of Claim 24 wherein said first electronic component is shielded from said second electronic component by said first shield and said second shield.

26. (Original) The electronic component package of Claim 24 wherein said first shield is grounded separately from said second shield.

27. (Original) The electronic component package of Claim 24 wherein said first shield and said second shield are commonly grounded.

28. (Original) The electronic component package of Claim 27 wherein said first shield is electrically coupled to said second shield.

29. (Original) The electronic component package of Claim 24 wherein said first shield ring and said second shield ring share a common side.

30-44. (canceled)